

RoHS  HF 466 Series Fuse


Description



The 466 Series Fast-Acting Surface Mount Fuse (SMF) is a small (1206 size) thin-film device designed for secondary protection of circuits used in space constrained applications such as hand-held portable electronic devices.

This series is 100% lead-free and meets the requirements of the RoHS directive. New Halogen-Free 466 Series fuses are available—to order use the “HF” suffix. See Part Numbering section for additional information.

Features

- Product is compatible with lead-free solders and higher temperature profiles.
- Product is marked on top surface with code to allow amperage rating identification without testing.
- Low profile for height sensitive applications.
- Flat top surface for pick-and-place operations.
- Element covering material is resistant to industry standard cleaning operations.
- Mounting pad and electrical performance is identical to Littelfuse 429 and 433 Series products.
- Alloy based element construction provides superior inrush withstand characteristics (I^2t) over ceramic or glass based 1206 chip fuse products.

Agency Approvals

AGENCY	AGENCY FILE NUMBER	AMPERE RANGE
	E10480	125MA - 5A
	LR29862	125MA - 5A

Electrical Characteristics for Series



% of Ampere Rating	Opening Time at 25°C
100%	4 hours, Minimum
200%	5 sec., Maximum
300%	0.2 sec., Maximum

Applications

Secondary protection for space constrained applications:

- Cell phones
- Battery packs
- Digital cameras
- DVD players
- Hard disk drives.

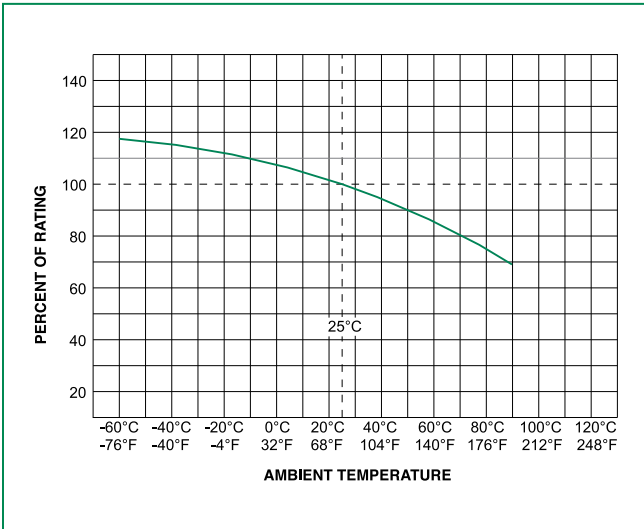
Electrical Specifications by Item

Ampere Rating (A)	Amp Code	Max Voltage Rating (V)	Interrupting Rating	Nominal Cold Resistance (Ohms)	Nominal Melting I^2t (A ² sec)	Nom Voltage Drop (mV)	Nom Power Dissipation (W)	Agency Approvals	
									
0.125	.125	125	50A @125 V AC/DC	4.000	0.00040	552.66	0.0691	x	x
0.200	.200	125		1.160	0.00055	254.28	0.0509	x	x
0.250	.250	125		0.710	0.0010	207.01	0.0518	x	x
0.375	.375	125		0.350	0.0028	169.18	0.0634	x	x
0.500	.500	63	50A @63 V AC/DC	0.248	0.0060	158.47	0.0792	x	x
0.750	.750	63		0.111	0.0276	98.65	0.0740	x	x
1.00	001.	63		0.076	0.0423	89.94	0.0899	x	x
1.25	1.25	63		0.059	0.0640	85.71	0.1071	x	x
1.50	01.5	63		0.048	0.1103	82.97	0.1244	x	x
1.75	1.75	63		0.039	0.1323	80.73	0.1413	x	x
2.00	002.	63	50A @32 V AC/DC	0.031	0.2326	78.73	0.1575	x	x
2.50	02.5	32		0.024	0.3516	76.99	0.1925	x	x
3.00	003.	32		0.020	0.5760	75.99	0.2280	x	x
4.00	004.	32		0.014	1.024	74.50	0.2980	x	x
5.00	005.	32		0.011	1.600	73.75	0.3688	x	x

1. Measured at 10% of rated current, 25°C.

2. Measured at rated voltage.

Temperature Derating Curve



Note:

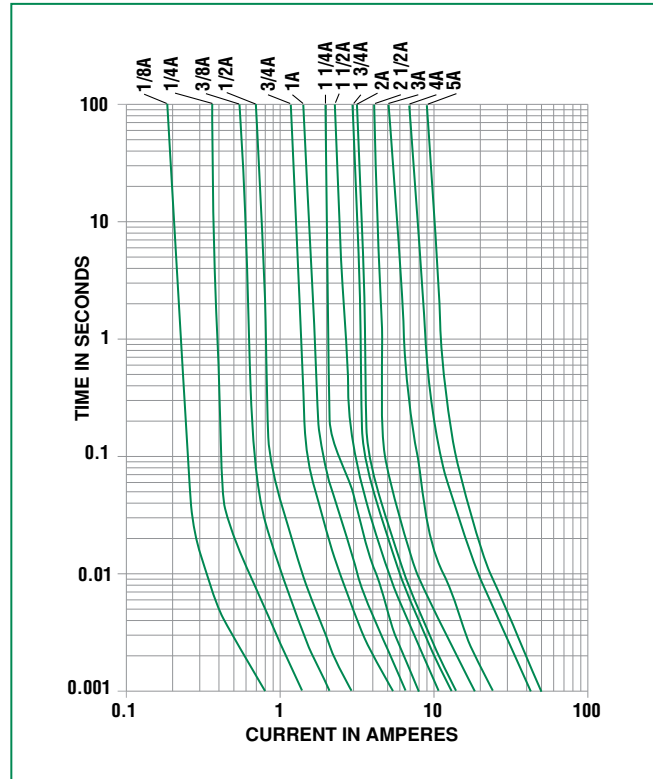
- Derating depicted in this curve is in addition to the standard derating of 25% for continuous operation.

Example:

For continuous operation at 70 degrees celsius, the fuse should be derated as follows:

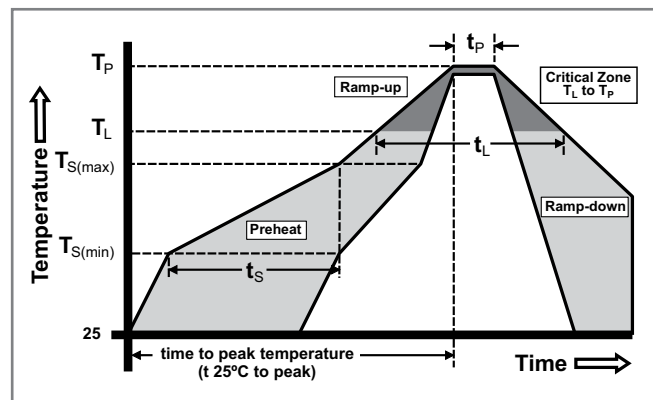
$$I = (0.75)(0.80)I_{RAT} = (0.60)I_{RAT}$$

Average Time Current Curves



Soldering Parameters

Reflow Condition		Pb – Free assembly
Pre Heat	- Temperature Min ($T_{s(min)}$)	150°C
	- Temperature Max ($T_{s(max)}$)	200°C
	- Time (Min to Max) (t_s)	60 – 180 secs
Average ramp up rate (Liquidus Temp (T_L) to peak)		5°C/second max
$T_{s(max)}$ to T_L - Ramp-up Rate		5°C/second max
Reflow	- Temperature (T_L) (Liquidus)	217°C
	- Temperature (t_L)	60 – 150 seconds
Peak Temperature (T_p)		250 ^{+0/-5} °C
Time within 5°C of actual peak Temperature (t_p)		20 – 40 seconds
Ramp-down Rate		5°C/second max
Time 25°C to peak Temperature (T_p)		8 minutes Max.
Do not exceed		260°C



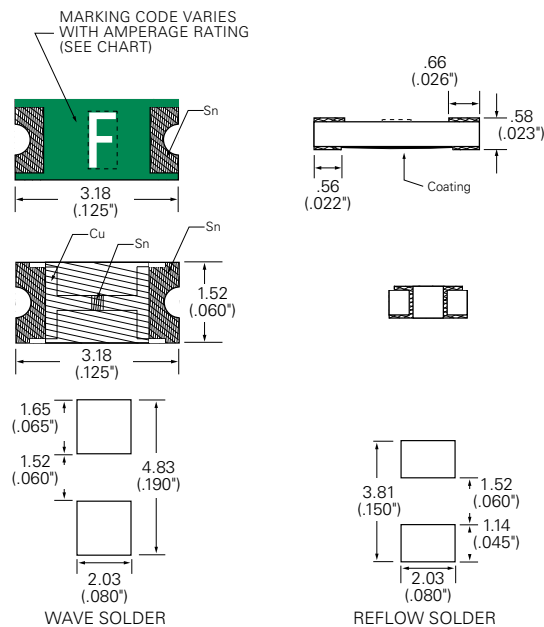
Wave Soldering	260°C, 10 seconds max.
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Product Characteristics

Materials	Body: Advanced High Temperature Substrate Terminations: 100% Tin over Nickel over Copper Element Cover Coat: Conformal Coating
Operating Temperature	- 55°C to 90°C. Consult temperature derating curve chart.
Thermal Shock	Withstands 5 cycles of -55°C to 125°C
Humidity	MIL-STD-202F, Method 103B, Condition D

Vibration	Per MIL-STD-202F, Method 201A
Insulation Resistance (After Opening)	Greater than 10,000 ohms
Resistance to Soldering Heat	MIL-STD-202G, Method 210F, Condition D

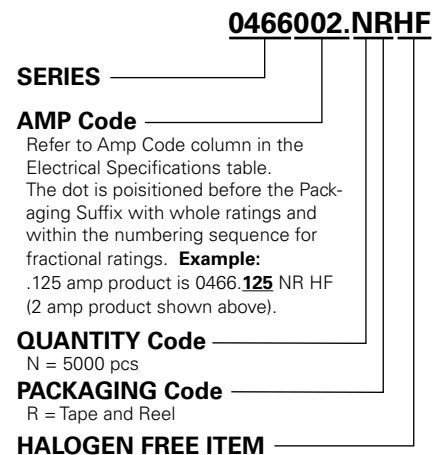
Dimensions



Part Marking System

Amp Code	Marking Code
.125	B
.200	C
.250	D
.375	E
.500	F
.750	G
001.	H
1.25	J
01.5	K
1.75	L
002.	N
02.5	O
003.	P
004.	S
005.	T

Part Numbering System



Packaging

Packaging Option	Packaging Specification	Quantity	Quantity & Packaging Code
8mm Tape and Reel	EIA RS-481-2 (IEC 286, part 3)	5000	NR